



Material Content Data Sheet



Halogen-Free

Sales Product Name	SLE 66R08P MCC8I	Issued	27. April 2022
MA#	MA005733540		
Package	P-MCC8-2-6	Weight*	36.67 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.031	2.81	2.81	28109	28109
leadframe	non noble metal	tin	7440-31-5	1.468	4.00		40041	
	non noble metal	copper	7440-50-8	23.004	62.73	66.73	627307	667348
wire	noble metal	gold	7440-57-5	0.037	0.10	0.10	1017	1017
encapsulation	organic material	carbon black	1333-86-4	0.101	0.28		2752	
	plastics	epoxy resin	-	2.220	6.05		60543	
	inorganic material	silicondioxide	60676-86-0	7.771	21.19	27.52	211900	275195
leadfinish	noble metal	silver	7440-22-4	0.339	0.92	0.92	9249	9249
plating	noble metal	silver	7440-22-4	0.572	1.56	1.56	15597	15597
glue	inorganic material	silica	112945-52-5	0.002	0.01		61	
	miscellaneous	miscellaneous	-	0.006	0.02		160	
	plastics	epoxy resin	-	0.120	0.33	0.36	3264	3485
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com